



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC014N06NST	Issued	03. June 2021
MA#	MA005425569		
Package	PG-TDSON-8-26	Weight*	115.69 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.818	1.57	1.57	15719	15719
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		134	
	non noble metal	iron	7439-89-6	0.052	0.04		448	
	non noble metal	copper	7440-50-8	51.740	44.75	44.80	447254	447836
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	387	387
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		694	
	plastics	epoxy resin	-	6.343	5.48		54833	
	inorganic material	silicondioxide	60676-86-0	33.724	29.15	34.70	291515	347042
leadfinish	non noble metal	tin	7440-31-5	1.392	1.20	1.20	12029	12029
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1675	1675
solder	non noble metal	tin	7440-31-5	0.050	0.04		431	
	noble metal	silver	7440-22-4	0.062	0.05		538	
	non noble metal	lead	7439-92-1	2.380	2.06	2.15	20571	21540
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			44	
	non noble metal	iron	7439-89-6	0.017	0.01		148	
	noble metal	silver	7440-22-4	0.635	0.55		5493	
	non noble metal	copper	7440-50-8	17.131	14.81	15.37	148087	153772
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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